Optimizations of Defect Filter Layers for 1.3-μm InAs/GaAs Quantum-Dot Lasers Monolithically Grown on Si Substrates

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Abstract—III–V semiconductors monolithically grown on Si substrates are expected to be an ideal solution to integrate highly efficient light-emitting devices on a Si platform. However, the lattice mismatch between III–V and Si generates a high density of threading dislocations (TDs) at the interface between III–V and Si. Some of these TDs will propagate into the III–V active region and lead to device degradation. By introducing defect filter layers (DFLs), the density of TDs propagating into the III–V layers can be significantly reduced. In this paper, we present an investigation on the development of InGaAs/GaAs strained-layer superlattices as DFLs for 1.3-μm InAs/GaAs quantum-dot lasers monolithically grown on a Si substrate. We compare two broad-area InAs/GaAs quantum-dot lasers with non-optimized and optimized InGaAs/GaAs DFLs. The laser device with optimal DFLs has a lower room-temperature threshold current density of 99 A/cm² and higher maximum operation temperature of 88 °C, compared with 174 A/cm² and 68 °C for the reference laser.

Index Terms—Molecular beam epitaxy, quantum dots, semiconductor lasers, silicon photonics.

I. INTRODUCTION

In order to achieve fast chip-to-chip and system-to-system optical communication with Si photonic integrated circuits, Si–based efficient and reliable light emitting sources are required. A Si–based light-emitting source has long been considered the “holy grail” of Si photonics because of the challenges involved. Bulk Si and Ge have an indirect bandgap, and thus are not efficient light-emitting materials [1], [2]. Until now, novel approaches including hybrid monolithic integration of III–V/Si, stimulated Raman scattering and Ge/Si laser, have been developed for silicon-based lasers. However, Si Raman lasers are restricted by the need for off-chip optical pumping [3], [4], while Ge/Si lasers suffer from extremely high threshold current density (>300 kA/cm²) and high optical loss [5].

Recently, the heterogeneous integration of III–V semiconductors on Si platforms has demonstrated lasers with milliwatt power output and high operating temperature (>100 °C) by using wafer-bonding techniques [6]. However, the issues of yield and reliability for this approach still remain. III–V materials monolithically grown on Si substrates have been proposed as an ideal solution for photonic integration on Si, i.e., by growing GaAs or InP buffer layers directly on Si substrates [7], [8]. The major issue for this method is the formation of threading dislocations (TDs) due to the lattice and thermal expansion coefficient mismatch between the III–V materials and Si [9] and antiphase domains (APDs) due to the polar to non-polar epitaxial growth [10]. APDs can be eliminated by growing III–V materials on off-cut Si substrates and using a two-step growth method [11]. For the epitaxial growth of III–V materials on Si substrates, optimization of the buffer layers, including the GaAs buffer layer and defect filter layers (DFLs), plays a crucial role in reducing the threading dislocation density from 10¹⁰ cm⁻² at the GaAs/Si interface to 10⁶ cm⁻² at the active region [12], [13]. Yang et al. demonstrated the pulsed operation of a 1.1 μm InAs/GaAs quantum dot (QD) laser on a Si substrate by using QD DFLs [14] and Nakamura et al. have used AlGaInN/GaN strained-layer superlattices (SLSs) as DFLs to achieve a multi-quantum-well laser on GaN [15].

QDs possess unique properties that can lead to lasers with ultra-low threshold currents, temperature insensitivity and reduced sensitivity to TDs [16]–[22]. Therefore, a combination of high efficacy DFLs and III-V QDs has been considered to be the most attractive approach for achieving III–V/Si lasers. Indeed, based on this technique, Wang et al. reported the first 1.3-μm InAs/GaAs QD lasers monolithically grown on Si substrates [23], while Chen et al. and Jiang et al. demonstrated the first InAs/GaAs QD SLDs monolithically grown on Si and Ge substrates [24], [25]. Likewise, continuous-wave operation of InAs/GaAs QD lasers monolithically grown on Ge/Si substrates have been reported recently [26]–[29].

To obtain practical lasers on Si, further reduction in dislocation density in the III–V buffer layer is required, and hence more efficient DFLs are needed. In this paper, we report the optimizations of the DFLs by adjusting growth conditions and structures of InGaAs/GaAs SLs. The optimization involves...
**in-situ** thermal annealing, variation of indium composition in the SLSs, and variation of GaAs thickness in the SLSs. Finally, the performance of two InAs/GaAs QD lasers monolithically grown on Si substrates under non-optimized and optimized conditions was compared. The optimization of DFLs leads to significant improvements of QD lasers, including reduction of threshold current density from 174 to 99 $A/cm^2$ and increase of maximum operation temperature from 66 to 88 $°C$.

**II. GROWTH STRUCTURE**

The QD structures were grown by solid-source molecular beam epitaxy (MBE). As shown in the schematic image in Fig. 1, five layers of InAs/GaAs QDs were monolithically grown on n-doped Si substrates (1 0 0) with 4° offcut oriented to (0 1 1) after introducing a 1 $μm$ GaAs buffer layer and three sets of InGaAs/GaAs SLSs. Before the growth, oxide desorption of the Si substrate was performed at 900 $°C$ for 30 min. The 1 $μm$-GaAs buffer layer was grown in two steps: low temperature growth of 30 nm GaAs with a growth rate of 0.1 monolayers/s (ML/s) at 380 $°C$ followed by high temperature growth of 970 nm GaAs grown with 0.7 ML/s. The two-step growth helps to confine most of the TDs at the interface region. To further reduce the threading dislocation density, the three sets of InGaAs/GaAs DFLs were grown after the first 1 $μm$ GaAs buffer layer. Each set of DFLs consisted of five periods of InGaAs/GaAs SLSs and separated by a 350 nm GaAs spacer layer. To improve the effectiveness of InGaAs/GaAs DFLs, we introduced two different growth methods for the DFLs. As shown in Fig. 2, in the growth method I, a GaAs spacer layer was grown during the period of heating up to 610 $°C$ right after the deposition of InGaAs/GaAs SLSs at 420 $°C$. In contrast, in growth method II, GaAs spacer layer was grown after in-situ annealing of the SLSs at 610 $°C$. Additionally, the efficacy of indium composition $x$ and GaAs thickness in the SLSs has also been studied by using $x = 0.16$, 0.18 and 0.20 for indium compositions and 8, 9 and 10 nm for GaAs thickness.

For the growth of the active region, five InAs/InGaAs dot-in-a-well (D WELL) layers were grown [30]. About 3 MLs of InAs with 0.1 ML/s growth rate were deposited on 2 nm of InGaAs and then capped by 6 nm of InGaAs and 5 nm of GaAs. The QDs were grown at 510 $°C$ while each layer of InAs/GaAs QDs was separated by 45 nm of GaAs spacer layer. The DWELLs were embedded between two 100-nm GaAs layers grown at 580 $°C$ and 50-nm AlGaAs layers grown at 610 $°C$. The QD density is around $3.8 \times 10^{10}$ cm$^{-2}$ as presented in Fig. 3.

**III. EFFECTS OF INGaAs/GaAs DFLS ON THE MATERIAL QUALITIES OF III–V MATERIALS GROWN ON SI SUBSTRATES**

In Table I, QD densities and photoluminescence (PL) peak intensities are compared for each step of optimizations including modifying growth methods of GaAs spacer layer, indium composition and GaAs thickness in In$_x$Ga$_{1-x}$As/GaAs DFLs.
Growth methods I and II have been applied to samples A and B, respectively. For the samples B, C and D, the indium composition in InGaAs/GaAs SPL has been varied from $x = 0.16$ to 0.20. Samples B, E and F have been grown using 8, 9 and 10 nm of GaAs inside each $\text{In}_x\text{Ga}_{1-x}\text{As}/\text{GaAs}$ SLS, respectively.

The PL measurements were performed using 635-nm solid-state laser excitation at room temperature. The PL spectrum in Fig. 4(a) shows that sample B has three times stronger emission of ground state than sample A. Sample B’s separation between ground state and excited state is 60 meV, which is slightly larger than 56 meV of sample A. The PL measurements show an improved optical property of sample B using growth method II compared with sample A using growth method I. The reason for this improvement in PL intensity can be understood in terms of the improved material quality after using in-situ annealing of SLSs. After the growth of InGaAs/GaAs at low temperature, the annealing of SLSs and high temperature growth of GaAs increase the dislocation motions, which helps the dislocations to meet and eliminate each other. As a result, less non-radioactive recombination is expected in the QD region due to reduced density of TDs.

As presented in Fig. 4(b), sample B exhibits PL intensity that is approximately 30% and 40% greater than samples C and D, respectively. This proves that the indium composition of 0.18 in $\text{In}_x\text{Ga}_{1-x}\text{As}/\text{GaAs}$ SLSs contributes the best crystal quality compared with the other indium compositions used. The remarkable improvement observed in PL intensity is due to a good balance between generation of strain-induced defects and annihilation of dislocations. A higher indium composition in InGaAs/GaAs SLSs is able to increase strain and block more TDs from propagating. On the other hand, the larger strain could introduce new TDs, and hence undermine the dislocation filtering efficiency of SLSs and degrade the structural and optical qualities of epilayers.

Cross-sectional transmission electron microscopy (TEM) measurements have been performed to examine the crystal quality further and compare the effectiveness of the DFLs of each sample. As shown in the bright-field TEM images in Fig. 5(a), a large number of dislocations appear at the interface of GaAs/Si. Most of the dislocations are trapped in the first 200 nm due to self-annihilation. However, there are still a considerable number of TDs propagating towards the active region. After
Fig. 5. (a) dark-field TEM cross-sectional TEM image of three layers of InGaAs/GaAs SLSs DFLs. (b) Bright-field TEM cross-sectional image of DFLs on GaAs buffer layer and Si substrate.

Introduction of the DFLs the annihilation of TDs has been significantly enhanced. As shown in Fig. 5(a) and (b), the majority of TDs have been blocked by three sets of DFLs. As a result, the material quality and then device performance are largely dependent on the efficiency of DFLs.

To examine the efficiency of different types of DFL, we have measured dislocation density just above each layer of DFL using TEM measurements. We define the efficiency of DFL as the fraction of TDs it removes, which can be expressed as

\[
\text{Efficiency} = 1 - \frac{n(\text{experiment})}{n(\text{predict})}
\]

where \(n(\text{experiment})\) is the number of dislocations counted just above the DFL and \(n(\text{predict})\) is the number of dislocations predicted by the equation describing “natural” decrease in \(\rho_{TD}\) [32]. The dislocation density \(\rho_{TD}\) with natural decay is related to the thickness \(h\) and can be expressed as

\[
\rho_{TD} = Ah^{-0.5}
\]

where \(A\) is a constant fitted by the counts of TDs at three positions in the GaAs buffer layer: 300, 600 and 900 nm. The efficiencies of each type of DFLs are presented in Fig. 6. For the first set of DFL, the efficiencies of four samples A, B, C, and D range from 40% to 50%. After the first set of DFL, samples B, C and D show a stronger increase in efficiency compared with sample A. This is due to the \textit{in situ} thermal annealing and high temperature GaAs spacer layer growth, which successfully increase the dislocation motion and hence the opportunities for the elimination of TDs. Moreover, sample B with In\(_{0.18}\)Ga\(_{0.82}\)As in the SLSs show the highest filtering efficiency for the second and third sets of DFLs. The highest efficiency observed in sample B confirms a good balance between generation of strain-induced defects and annihilation of dislocations. Compared with the other samples, the significant reduction in the efficiency of the third DFL of sample C with only 16% indium in SLSs indicates inefficient interaction between strain relaxation and TDs when only a low density of threading dislocation is presented. Therefore, the sample B with 18% indium composition in InGaAs/GaAs DFLs and growth method II has been proved to be the most effective in reducing the density of TDs.

To gain further insight into the effects of DFLs, we have also compared different thicknesses of GaAs in the InGaAs/GaAs SLSs. From Fig. 4(c) it can be observed that samples B and E have similar PL spectra but the intensity for sample F is significantly lower. This clearly shows that the 8-nm GaAs (sample F) thickness is too small and the accumulated strain degrades the material quality, leading to a drop in the PL intensity by nearly a half. The PL of samples B and E are comparable because the thicker GaAs spacers provide enough buffer for strain-induced generation of defects while maintaining suitable strain relaxation of the In\(_{0.18}\)Ga\(_{0.82}\)As/GaAs SLS for interacting with TDs. This is in good agreement with the TEM measurements of the samples with the same thickness but different indium compositions.

IV. LASER FABRICATION AND PERFORMANCE

To further investigate the effect of InGaAs/GaAs SLSs DFLs, full laser structures have been grown and processed. The GaAs buffer layer and InAs/GaAs DWell active region were grown under the same conditions as previously; samples A to F. We have grown two laser samples R1 and R2 that were based on the DFL growth conditions of samples A and B, respectively. After
four sets of DFLs, n and p type 1.2-\(\mu\)m-thick AlGaAs cladding layers were grown on the bottom and then on top of the active region.

The broad-area laser devices were fabricated. The 50 \(\mu\)m wide ridges were created by standard lithography and wet etching techniques. We etched down the ridges to 200 nm below the active region, so as to improve the carrier confinement. We deposited InGe/Au and Ti/Pt/Au on the GaAs n and p contact layers, respectively. Both n and p contact layers are face-up. The cavity length of the devices is 3 mm and no facet coating was applied.

Measurements of single facet output power against current density for two Si-based InAs/GaAs QD lasers are presented in Fig. 7(a) and (b). During the measurements, the laser devices were mounted epi-side up with a sub-mount temperature of 18 °C without active cooling. The lasers were electrically pumped under pulsed conditions of 1% duty cycle and 1 \(\mu\)s pulse width. The threshold current densities of R1 and R2 are 174 and 99 A/cm\(^2\), respectively. The lower threshold current densities from sample R2 proves that the optimized InGaAs/GaAs DFLs improve the laser performance in terms of lower threshold current density, which is due to the elimination of the majority of TDs within the GaAs buff spacer layer. The maximum operation temperature of R2 is 88 °C, which is higher than R1’s maximum operation temperature of 68 °C. In addition, compared with the previous reports, sample R2 shows lower threshold current density than InAs/GaAs QD lasers on Si substrate using InAlAs/GaAs SLSs which had a threshold current of 194 A/cm\(^2\) [13].

Fig. 7(c) shows the room-temperature lasing spectrum, which has been measured for an injection current of 105 A/cm\(^2\). It clearly shows that the laser is emitting at 1.28 \(\mu\)m, which matches the PL spectrum. Fig. 8 shows the temperature dependence \(J_{th}\) for laser samples R1 and R2. R2 shows an improved characteristic temperature \(T_0=40.2\) K, compared with sample R1 with \(T_0=27.3\) K for the temperature range 18 to 68 °C. The poor performance of \(T_0\) for R1 at the higher temperature range could be due to the increased non-radioactive recombination rate at high temperature range, due to the higher threading dislocation density compared with R2. The temperature stability of lasers can be improved by using p-type modulation doping to enhance the confinement of holes at high temperature [33].

**V. CONCLUSION**

In conclusion, we have investigated the optimization of InGaAs/GaAs SLSs DFLs by modifying (i) the GaAs spacer layer growth conditions, and (ii) the indium composition and GaAs thickness in InGaAs/GaAs SLSs. The effect of DFLs has also been studies in laser devices. The work confirms that the design and growth of DFLs play a critical role in the success of QD lasers monolithically grown on Si. Particular attention should be paid to enhancing the motion of TDs and well-controlled strain relaxation. Finally, with optimized DFLs in this work, an InAs/GaAs QD laser with a low threshold current density, high
operating temperature, and improved characteristic temperature has been demonstrated on a Si substrate. These results provide an essential step to the further improvement of the performance of InAs/GaAs QD lasers monolithically grown on a silicon platform.

REFERENCES


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